

THERMAL SOLUTIONS FOR NOTEBOOK PCs

COOLING: SPREADERSHIELD™ SOLUTIONS lower the temperature of a thermally sensitive heat source and generally require good contact with heat source.



ACTIVE COOLING

A SPREADERSHIELD™ solution is applied directly to the 1.6 GHz Intel® Atom Processor and the Mobile Intel® Express Chipset and next to the fan in order to achieve a complete cooling solution for the device.



PASSIVE COOLING

SPREADERSHIELD™ solutions eliminated the fan/sink assembly to reduce weight by 50% and conduct ~15W of heat to underside.



PASSIVE COOLING



SPREADERSHIELD solutions conduct heat from the 1 GHz microprocessor, graphics processor and DRAM into the magnesium case, reducing CPU temperature by 17° C.

Compressible pads are used to increase contact pressure, eliminate TIMs, and optimize thermal resistance between the GPU and SPREADERSHIELD solutions.



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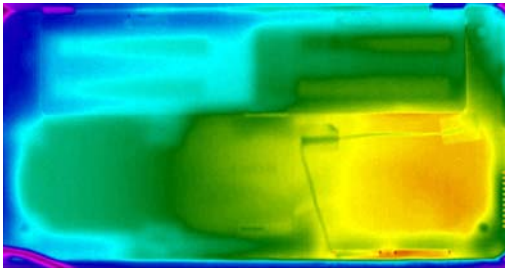
SHIELDING: SPREADERSHIELD™ SOLUTIONS lower the temperature of a thermally sensitive destination, and do not always require direct contact with heat source.



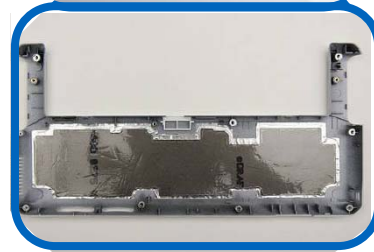
TOUCH TEMPERATURE REDUCTION

SPREADERSHIELD™ solution is adhered directly to the bottom case of a netbook.

This solution reduces the user touch temperature from the ~11.8W of heat generated by the 1.33 GHz Intel® Atom



Bottom Case WITH SPREADERSHIELD
8°C Reduction!!!



BATTERY SHIELDING

Four SPREADERSHIELD parts were included in this notebook application, two of which were directly used to shield the battery from the heat generated by the CPU/GPU

